

# SK-AM62B Design Package Folder and Files List



Table 1 lists names of the folders and file names in the folders along with the format for all the files that have been included in the SK-AM62B. The AM62B starter kit (SK) evaluation module (EVM) is a stand-alone test and development platform built around the AM62x system-on-a-chip (SoC). AM62x processors are comprised of a quad-core 64-bit Arm®-Cortex®-A53 microprocessor, single-core Arm Cortex-R5F microcontroller (MCU) and an Arm Cortex-M4F MCU. The product overview document is available on SK-AM62B product folder on TI.com for customers to review before downloading the single Zip folder.

**Table 1. Proc114A1**

FOLDER (1st Level)	FOLDER (2nd Level)	Files Inside	File Type
----	----	PROC114A1_Folders_Files_List	XLS
		2024 Important Notice	PDF
1_SCHEMATIC	PDF	PROC114A1(001)_Sch_With_Design_Updates..Notes_V1.0	PDF
	PDF -Backup_SK_Schematic	PROC114A1(001)_sch	PDF
	----	Schematic_Revision_Readme	PDF
	ORCAD	PROC114A1(001)_Sch_With_Design_Updates..Notes_V1.0	DSN
	ORCAD - Backup_SK_Schematic	PROC114A1_SCH	DSN
2_BOM	----	PROC114A1(001)_BOM_With_Design_Updates..Notes_V1.0	XLS
	Backup_SK_Schematic_BOM	PROC114A1(001)_BOM	XLS
3_Board_File	Allegro	PROC114A1_BRD	BRD
	Simulation Scorecard	AM62x_Simulation_Scorecard	PDF
	Altium_ASCII	PROC114A1_BRD	ALG
4_Gerber	ODBGBR	PROC114A1_ODBGBR	ZIP
	274X	PROC114A1_274xGBR	ZIP
	IPC-D-356_NETLIST	PROC114A1_BRD	IPC
5_Gerber_PDF	FAB	PROC114A1_FAB	PDF
	PCB LAYERS	PROC114A1-LAYERS	PDF
	Geber Layers	PROC114A1-LAYERS	PDF
6_Assembly_Models_Packag e	2D	PROC114A1_BASY	DXF
		PROC114A1_TASY	DXF
	3D	PROC114A1_3D_STEP	STP
	IDF	PROC114A1_BRD	EMP
		PROC114A1_BRD	EMN
	Assembly_Drawing_PDF	PROC114A1_ASSEMBLY	PDF
		PROC114A1_TASY	PDF
		PROC114A1_BASY	PDF
	STNL	art_aper + 8 x .ART files	ART
XY-REP	PROC114A1_XY-REP	XLS	
7_PCB_LAYER_STACKUP	---	SK-AM62B_PROC114A1_Layer_STACKUP	PDF

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## References

Texas Instruments, [\[FAQ\] AM625 / AM623 : Custom board hardware design - Design and Review notes for Reuse of SK-AM62B Schematics](#) article

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